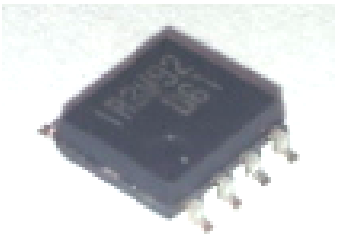
IR3M92N4

AC-DC conversion type IC for LED Lighting



■Description

IR3M92N4 is a AC/DC power supply IC for LED lighting which built-in power factor improvement circuit, quasi-resonant operation circuit and PWM dimming circuit.
Primary-side control by transformer realizes the constant current operation suitable for LED lighting.

■Features

1. Input voltage range :
   10V to 18V
   *VCC=23V(Max.) at start up.
2. Output current (LED current) :
   Constant current control
3. Feature Function :
   Power factor improvement, quasi-resonant operation,
   PWM dimming operation and Standby operation
4. Error detection / Protection :
   VCC under voltage lock-out
   Output over voltage lock-out
   Over temperature protection
   Over current protection
5. P-type silicon monolithic IC
6. Radiation-proof design :
   This product is not radiation-proof design.
7. Lead finish : Lead Free
8. 8 pin SOP plastic package

■Agency approvals/Compliance

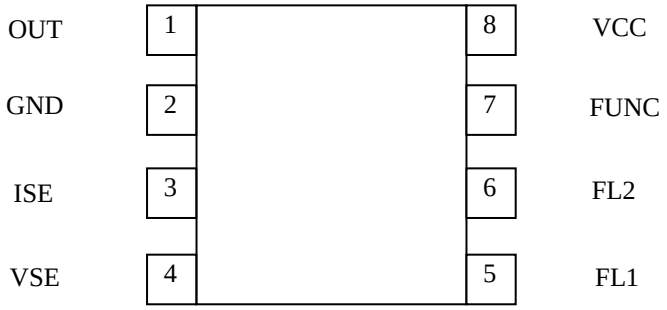
1. Compliant with RoHS directive (2002/95/EC)

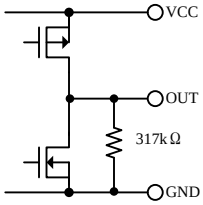
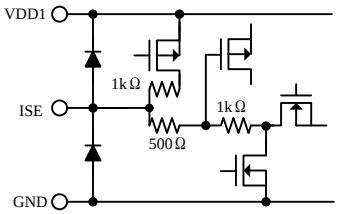
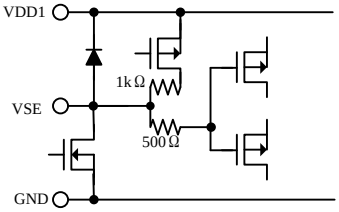
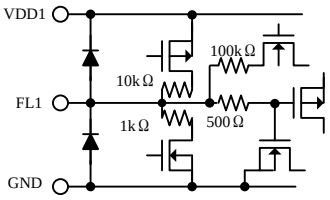
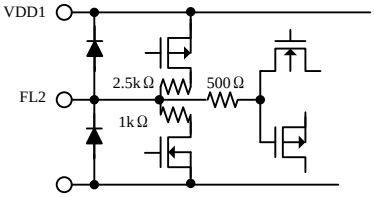
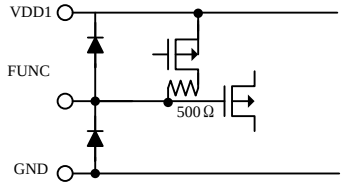
■Applications

1. Light bulb
2. Ceiling light
3. Tube light

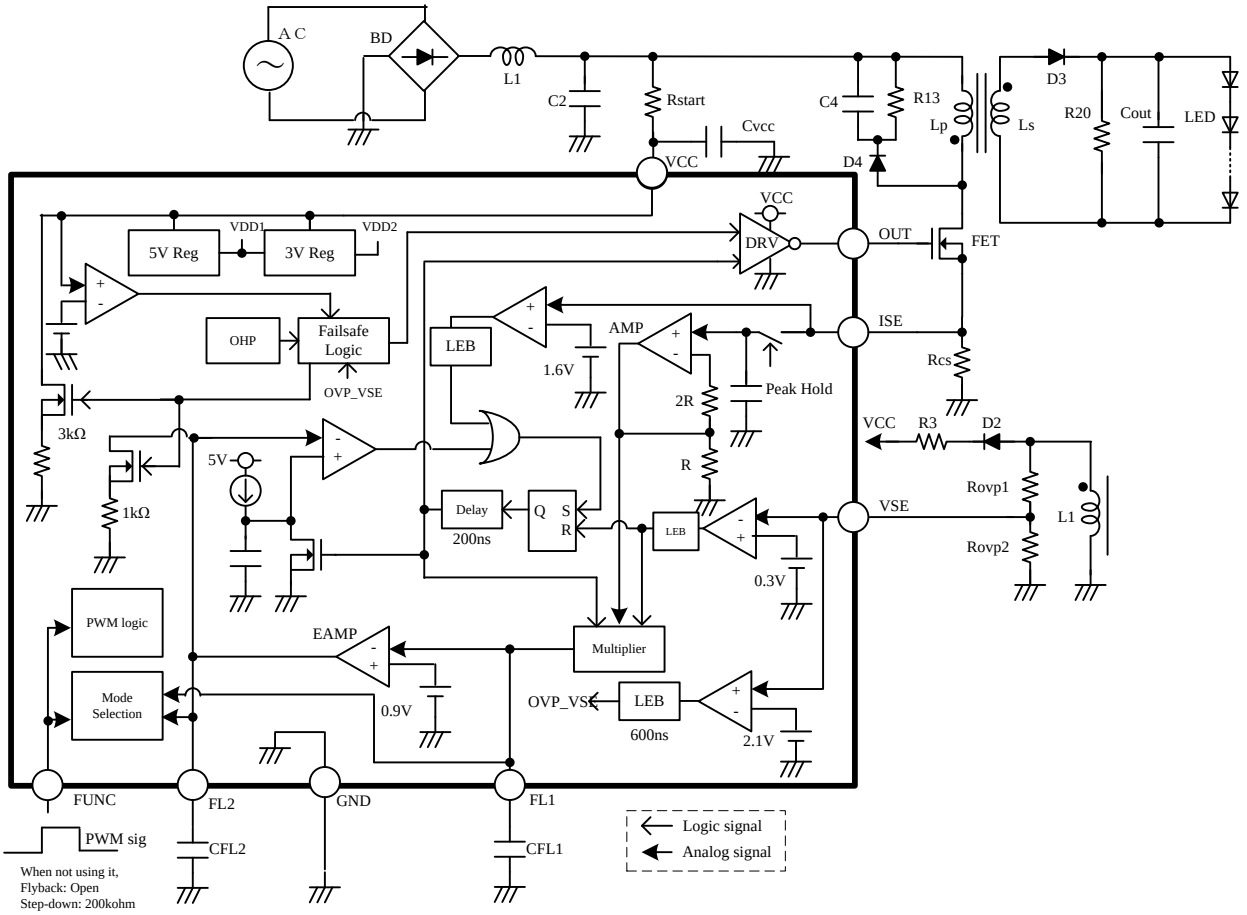
Sheet No.: OP13025EN

■Pin assignment



Pin name	Equivalent circuit	Pin description
①OUT		Gate drive for the external switching MOSFET
②GND		Ground terminal
③ISE		Current sense of the primary winding
④VSE		Voltage sense of the auxiliary winding
⑤FL1		The input terminal of error amplifier. Please connect capacitor CFL1 to this terminal.
⑥FL2		The output terminal of error amplifier. Please connect capacitor CFL2 to this terminal.
⑦FUNC		Mode setting terminal ・Flyback mode : Open ・Step-down mode : 200kohm ・PWM dimming input : pulse input ・Standby input terminal : GND
⑧VCC		Power Supply

■Block diagram and basic connection diagram



■Functional description

1. Constant current function

1-1. Concept of constant current operation (Flyback mode)

By monitoring VSE and ISE signals and controlling them, LED current (output current) can be controlled to be a constant level. Figure 1.2 shows FET Drain voltage, primary current and secondary current waveform during FET on and off. VSE signal is resistance-divided voltage of auxiliary winding output. Drain voltage waveform of FET and VSE waveform are same polarity and similar. As LED current (output current) is the average of secondary current, it is shown by equation (1).

$$\overline{Iout} = \frac{1}{2} \cdot Ipk2 \cdot \frac{Tres}{Tc} \qquad (1)$$

where Ipk2 : secondary peak current
Tres : period during secondary current flows
Tc : switching cycle

It is also shown by equation (2).

$$\overline{Iout} = \frac{1}{2} \cdot \frac{Np}{Ns} \cdot Ipk1 \cdot \frac{Tres}{Tc} \qquad (2)$$

where Np : primary winding turns
Ns : secondary winding turns
Ipk1 : primary peak current

As Np/Ns value is constant in equation(2), LED current (output current) can be controlled to be a constant value by keeping Ipk1・Tres/Tc constant. Ipk1 can be monitored by ISE terminal andTres can be monitored by VSE terminal.

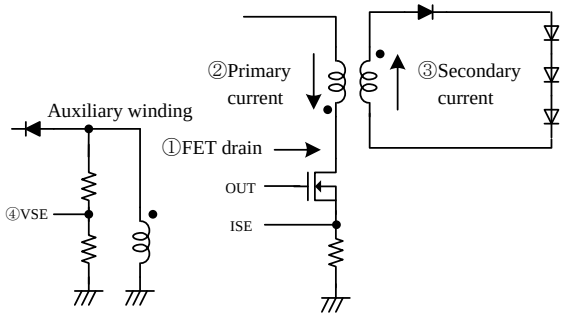


Figure 1.1 Circuit diagram

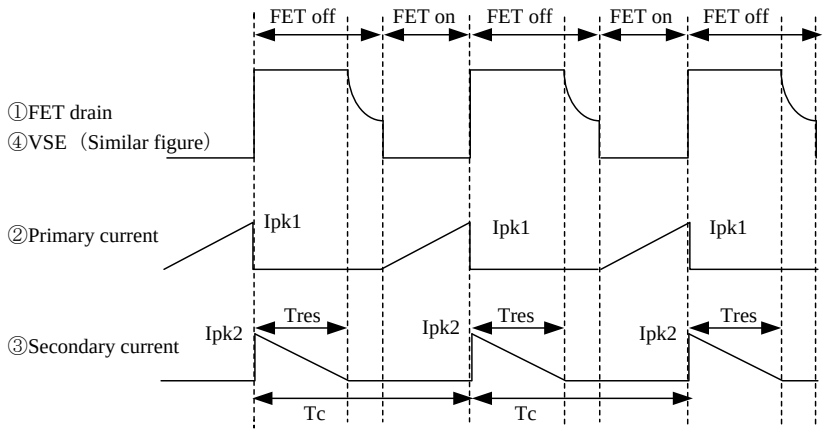


Figure 1.2 Waveform of each point of Figure 1.1 diagram

1-2. Constant current operation (Flyback mode)

IC operation, how to control LED current (output current) to be a constant value, is explained as below. Figure 1.3 shows block diagram relating constant current operation. As V_{ISE} is proportional to primary current and sensing resistance Rs, ISE terminal can monitor primary current. V_{PHOLD} is the output of peak hold circuit. It outputs the peak value of V_{ISE} every switching cycle, shown by equation (3).

$$V_{PHOLD} = Ipk1 \cdot Rs \qquad (3)$$

Multiplier divides Ipk1・Rs by Tres/Tc ratio.

$$V_{FL1} = Ipk1 \cdot Rs \cdot \frac{Tc}{Tres} \qquad (4)$$

Time constant of FL1 terminal should be set to much larger than switching period, where time constant of FL1 is decided by the resistance between the output of peak hold circuit and FL1 terminal (typ: 110 k ohm) and capacitor C_{FL1} connected to FL1 terminal. V_{FL1} shown by equation (4) is input of error amplifier, and is controlled to be equal to reference voltage Vref (0.9). FET on period is decided by the output of error amplifier.

In case of V_{FL1}< Vref , FET on period increases by VFL2 increase, which leads Ipk1 increase and V_{FL1} becomes to near Vref value. In case of V_{FL1}>Vref , FET on period decreases by VFL2 decrease, which leads Ipk1 decrease and V_{FL1} becomes to near Vref value. After all, V_{FL1} is controlled to be same value as Vref, and LED current (output current) is shown by equation (5), which is derived from equation (1), (2), (3), and (4).

$$\overline{Iout} = \frac{1}{2} \cdot \frac{Np}{Ns} \cdot \frac{Vref}{Rs} \qquad (5)$$

Equation (5) shows that LED current (output current) is decided by circuit constant value Np, Ns, and Rs.

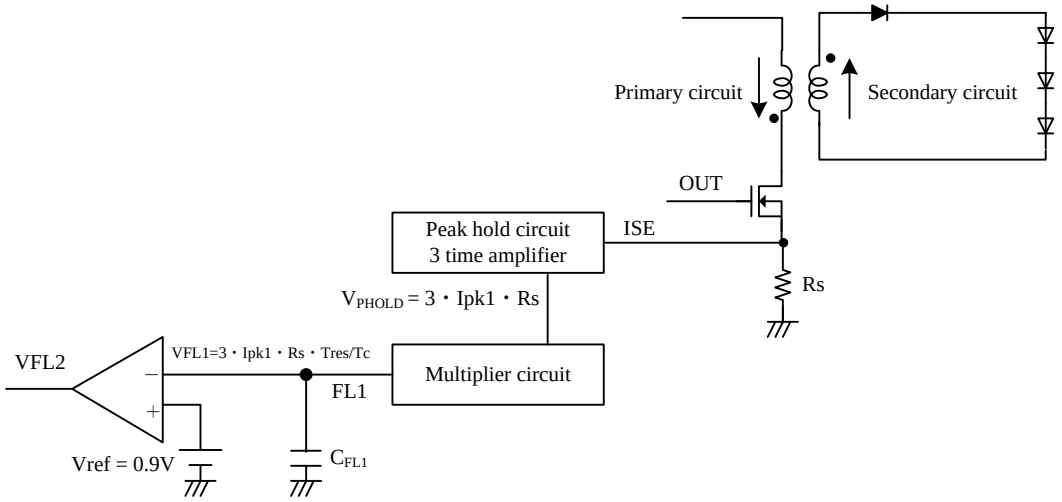


Figure 1.3 Block diagram relating constant current operation

2-1. Concept of constant current operation (Step-down mode)

Figure 1.4 shows FET Drain voltage, primary current and secondary current waveform during FET on and off. VSE signal is resistance-divided voltage of auxiliary winding output.
Drain voltage waveform of FET and VSE waveform are same polarity and similar. As LED current (output current) is the average of secondary current, it is shown by equation (6).

$$\overline{Iout} = \frac{1}{2} \cdot Ipk1 \qquad (6)$$

where Ipk1 : primary peak current

LED current (output current) can be controlled to be a constant value by keeping Ipk1 constant. Ipk1 can be monitored by ISE terminal andTres can be monitored by VSE terminal.

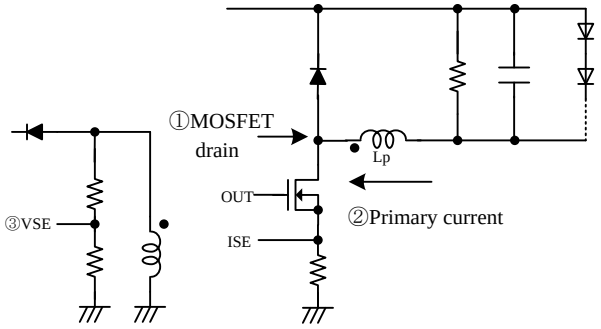


Figure 1.4 Circuit diagram

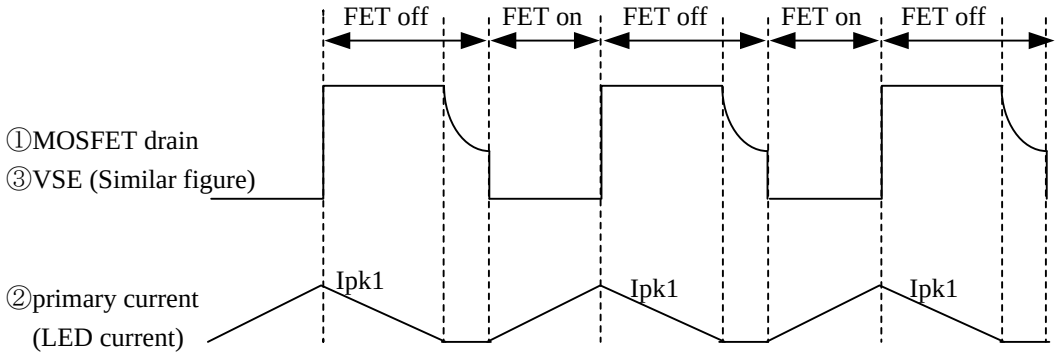


Figure 1.5 Waveform of each point of Figure 1.4 diagram

2-2. Constant current operation (Step-down mode)

IC operation, how to control LED current (output current) to be a constant value, is explained as below. Figure 1.6 shows block diagram relating constant current operation. As V_{ISE} is proportional to primary current and sensing resistance Rs, ISE terminal can monitor primary current. V_{PHOLD} is the output of peak hold circuit. It outputs the peak value of V_{ISE} every switching cycle, shown by equation (7).

$$V_{PHOLD} = Ipk1 \cdot Rs \qquad (7)$$

In Multiplier, VHOLD is outputted to FL1 terminal through internal 110kohm (TYP.).

$$V_{FL1} = Ipk1 \cdot Rs \qquad (8)$$

Time constant of FL1 terminal should be set to much larger than switching period, where time constant of FL1 is decided by the resistance between the output of peak hold circuit and FL1 terminal (typ: 110 k ohm) and capacitor C_{FL1} connected to FL1 terminal. V_{FL1} shown by equation (8) is input of error amplifier, and is controlled to be equal to reference voltage Vref (0.9). FET on period is decided by the output of error amplifier.

In case of V_{FL1}< Vref , FET on period increases by VFL2 increase, which leads Ipk1 increase and V_{FL1} becomes to near Vref value. In case of V_{FL1}>Vref , FET on period decreases by VFL2 decrease, which leads Ipk1 decrease and V_{FL1} becomes to near Vref value. After all, V_{FL1} is controlled to be same value as Vref, and LED current (output current) is shown by equation (9), which is derived from equation (6),(7) and (8).

$$\overline{Iout} = \frac{1}{2} \cdot \frac{Vref}{Rs} \qquad (9)$$

Equation (9) shows that LED current (output current) is decided by circuit constant value Rs.

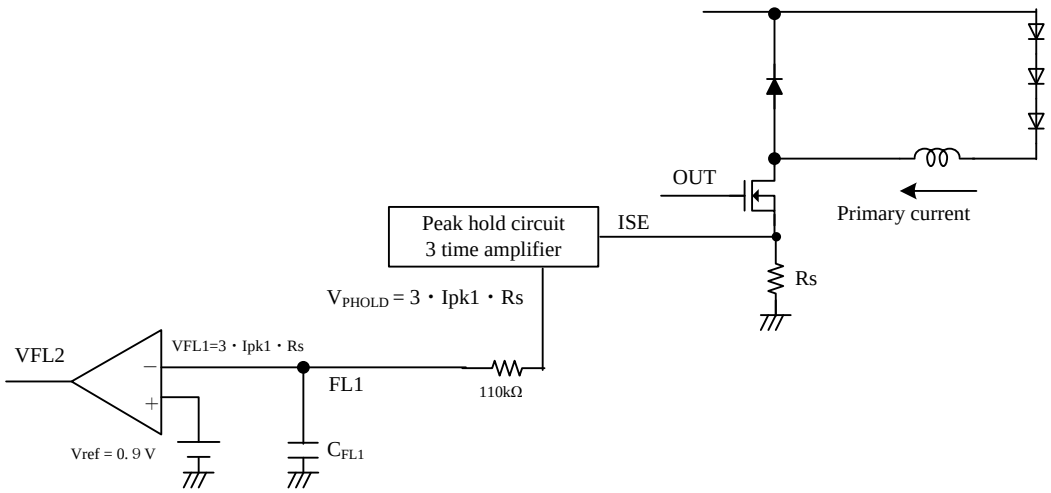


Figure 1.6 Step-down block diagram relation constant current operation

3. Power factor improvement by FET constant on-time control

Power factor improvement is explained as below. Changing period of FET on-time and flattery period of error amplifier are controlled to be much longer, compared to AC period (1/50Hz or 1/60Hz). As time constant of FL2 terminal shown by equation (10) is much larger than AC period, FET on-time can be considered to constant value during one AC cycle. where time constant of FL2 is decided by the output resistance of error amplifier 78kohm (TYP.) (@FL1=0.9V±0.3) and capacitor C_{FL2} connected to FL2 terminal (ex. 1uF).As Ton is constant value in equation (11), Ipk1 is proportional to Von.

$$\tau = R \cdot C = 78k\Omega \cdot 1uF = 0.078s \quad > 0.01s@AC50Hz \qquad (10)$$

$$Ipk1 = \frac{Ton}{L} \cdot Von = \alpha \cdot Von \qquad (11)$$

where L : primary winding inductance

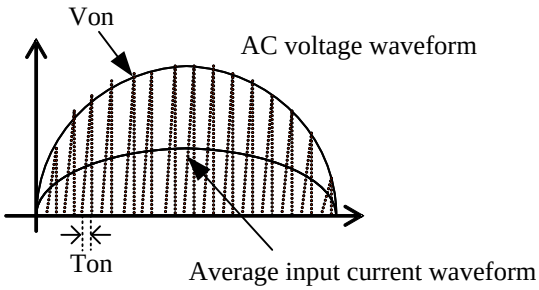


Figure 1.7 Power factor improvement

4. EMI improvement by quasi-resonant operation

EMI improvement by quasi-resonant operation is explained below. This IC operates in critical conduction mode. If it operates in discontinuous mode, after releasing transformer's energy, ringing occurs by parasitic inductance and capacitor of the transformer and FET, as shown in Figure 1.8. This ringing generates EMI noise. The moment when transformer release its energy completely is detected by VSE terminal, and this IC turns on FET at the bottom point of ringing waveform (quasi-resonant operation) as shown in Figure 1.9. Therefore this IC can minimizes EMI noise.

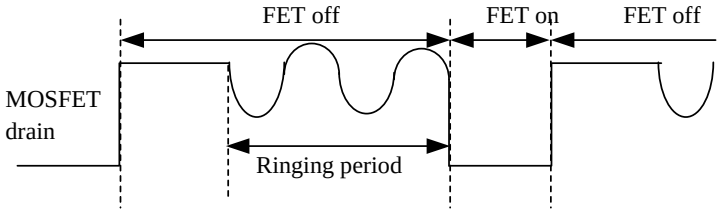


Figure 1.8 When FT is not driven on transition mode

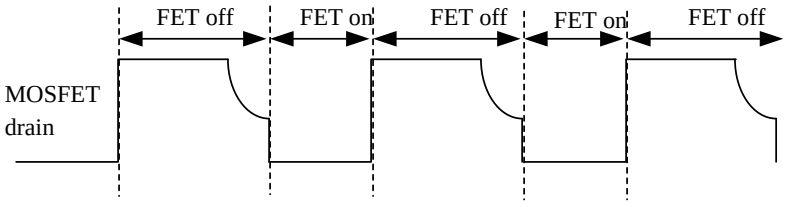


Figure 1.9 Quasi-resonant operation

5. Mode Judging Circuit

It is necessary to set up a FUNC terminal according to operational mode.
The input circuit of a FUNC terminal is shown in Fig. 1.10.
In the case of the flyback mode, please make a FUNC terminal open.
The example of connection of PWM dimming operation is indicated to Fig. 1.10.

Mode	FUNC terminal
Flyback	4.5V>FUNC>3.2V
Step-down	2.85V>FUNC>1.45V
Standby	0.8V>FUNC（※）

（※） It is necessary to input the voltage beyond 1.3V into the return from standby mode at FUNC terminal.

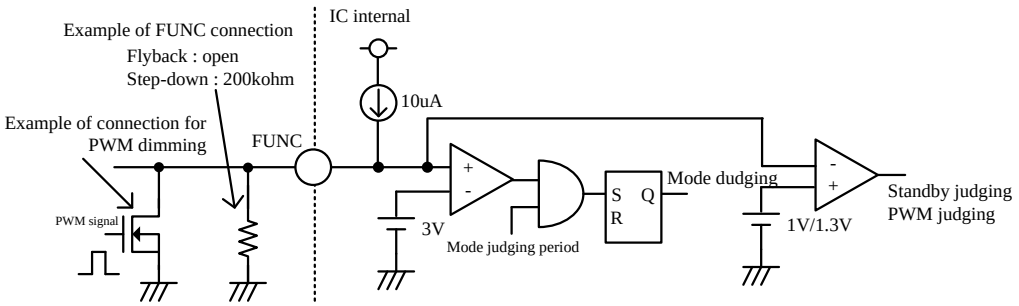


Figure 1.10 FUNC terminal input circuit diagram

A mode judging sequence is shown in Fig. 1.11.
In a-point, Va is starting voltage and it starts it by VCC=18V (TYP.).
MOSFET switching is started after a mode judging (a-point~b-point).
in FUNC terminal, PWM dimming becomes effective after a mode judging.

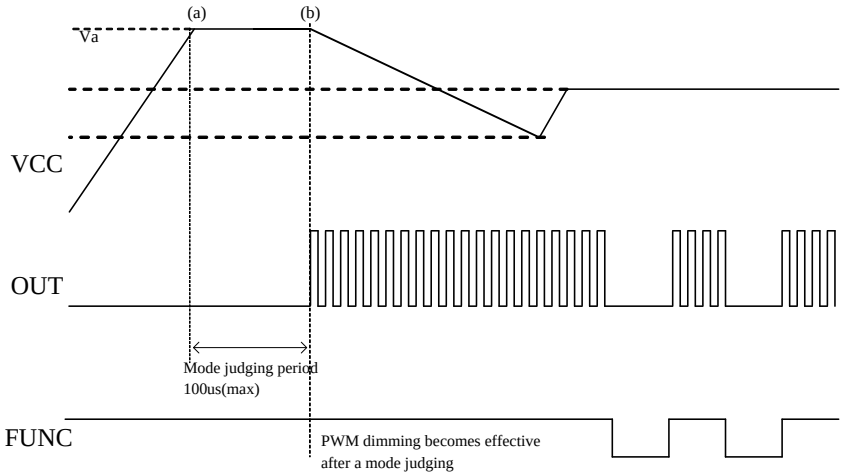


Figure 1.11 Mode judging sequence

A standby mode sequence is shown in Fig. 1.12.

When judged with standby mode in a mode judging period (a-point~b-point), a switching stop is kept. operation is stopped at Vb(UVLO voltage 6V (TYP.)), and the operation which will restart if the starting voltage 18V (TYP.) is reached ,is repeated.

The return from standby mode is carrying out a FUNC terminal more than 1.3V (e-point), discharges the capacity connected to VCC and becomes normal operation from the following restart timing (g-point).

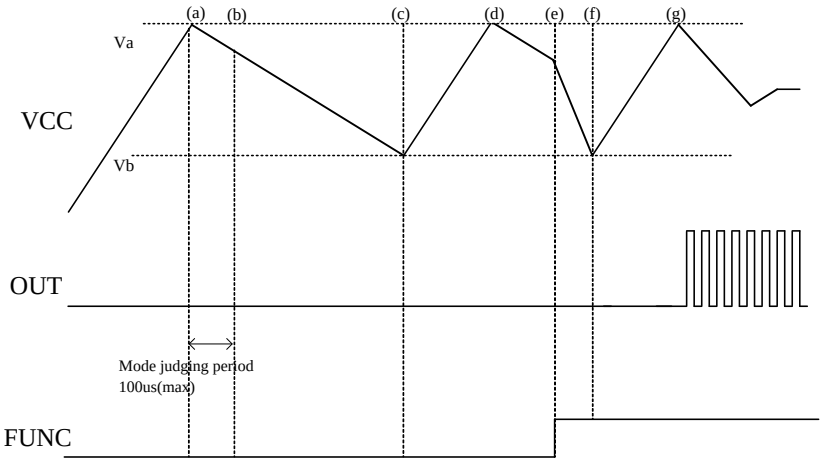


Figure 1.12 Standby mode sequence

6. PWM dimming Function

LED output current can be adjusted according to the PWM signal inputted into a FUNC terminal. The input condition of the PWM signal of a FUNC terminal becomes as follows, and shows operation in Fig. 1.13.

FUNC terminal	
4.5V>FUNC>1.45V	OUT: switching
0.8V>FUNC	OUT: OFF(※)

(※) In FUNC < 1V , the value of FL1 and FL2 is kept and the switching-on pulse is kept constant.

When a PWM function is used, please use it after are satisfactory or checking enough with the system, since sound may occur with a transformer, a coil, etc.

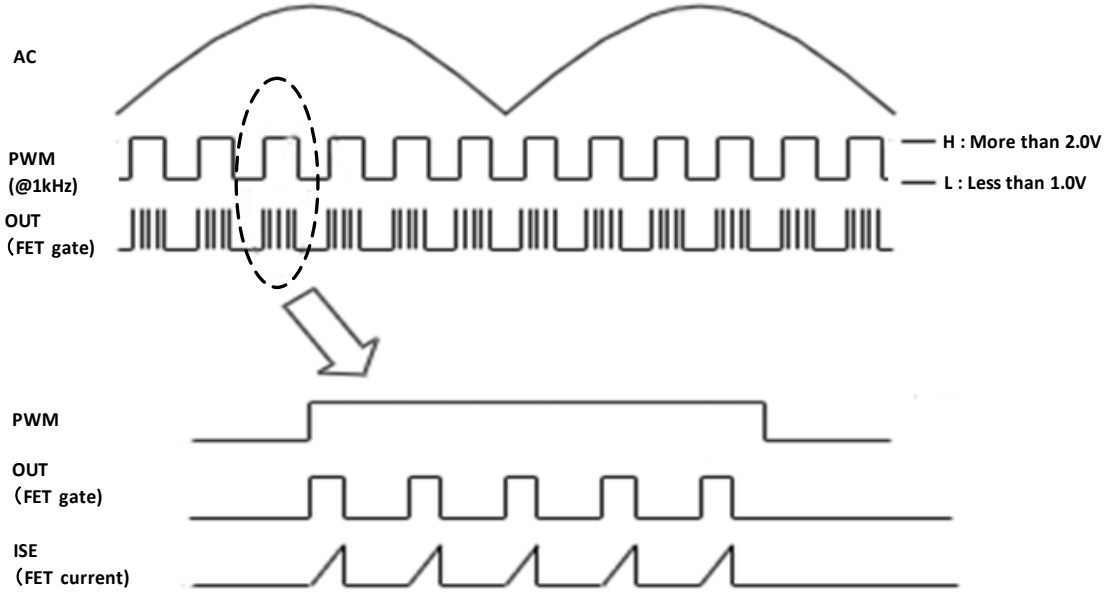


Figure 1.13 PWM dimming function

7. Error detection/Protection function

Over temperature protection, VCC under voltage lock-out, output Over voltage lock-out and Over current protection are built in this IC.

7-1. Over temperature protection

When junction temperature of this IC is over 150°C, thermal error is detected and following operation is performed.

- IC shut down
- Discharge CFL2 (Capacitor connected to CFL2)
- Discharge capacitor connected to VCC
- Discharge stops when VCC goes down to UVLO (6V)

7-2. VCC under voltage lock-out

IC operation stops when VCC voltage goes down to 6V(typ.) or less, because of VCC voltage down or short between VCC and GND. IC operation restarts when VCC voltage goes up to 18V or more (start up voltage).

7-3. Output over voltage lock-out

When VCC terminal and VSE terminal goes up to VOVP (Over voltage threshold voltage) or more, over voltage error is detected and following operation is performed.

- IC shut down
- Discharge CFL2 (Capacitor connected to CFL2)
- Discharge capacitor connected to VCC
- Discharge stops when VCC goes down to UVLO (6V).

Over voltage error is detected by VCC terminal voltage (typ. 22.7V) and VSE terminal voltage (typ. 2.1V). Over voltage threshold voltage is shown by equation (12).

$$V_{OVP\_VSE} \geqq 2.1V(TYP.) \ \& \ V_{OVP\_VCC} \geqq 22.7V(TYP.) \qquad (12)$$

where V_{OVP_VCC} : Over voltage threshold voltage for VCC
V_{OVP_VSE} : Over voltage threshold voltage for VSE

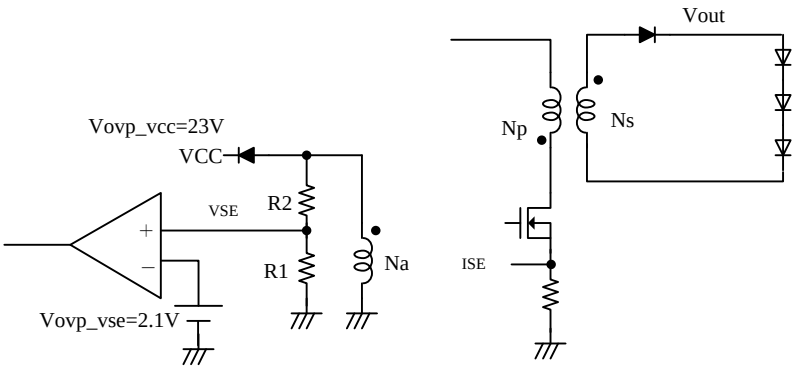


Figure 1.14 Circuit diagram

7-4. FET over current protection

When FET current goes up to VOCP (Over current threshold voltage) or more, over current error is detected and following operation is performed.

Cycle by cycle over current limit operation (default configuration).

- OUT turns Low and stops switching.
- IC do not shut down.
- OFF period will be more than 70us (typ.).

A waveform is shown in Fig. 1.16.

The voltage of ISE terminal at over-current detection is as follows.
The circuit configuration of over-current detecting is shown in Fig. 1.15.

Mode	over-current detection volgate
Flyback	ISE ≦ 1.6V(TYP.)
Step-down	ISE ≦ 0.8V(TYP.)

Over Current is detected by ISE terminal voltage(typ 1.6V). Over Current threshold voltage is shown as the figure below.

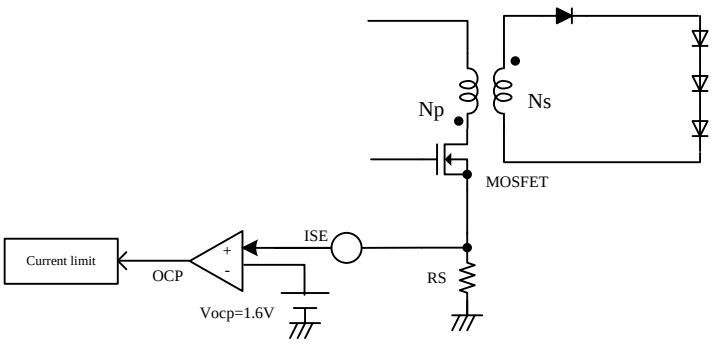


Figure 1.15 Circuit diagram relating over current protection

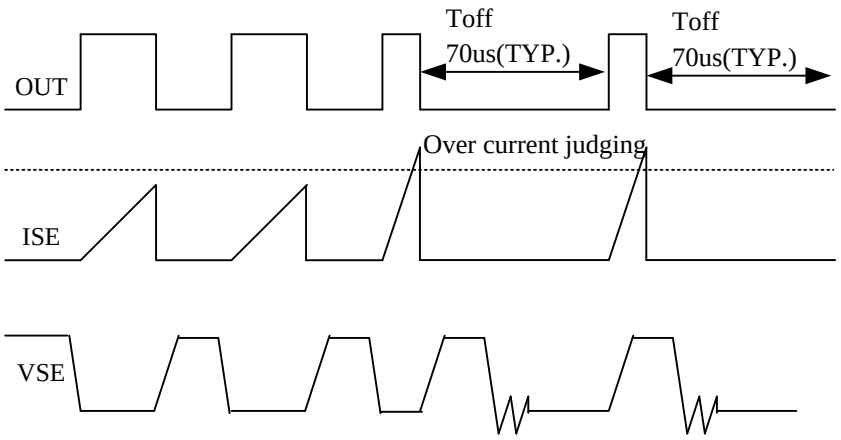


Figure 1.16 Over current judging waveform

8. Start-up sequence

Figure 1.17 shows start-up sequence waveform. This IC starts up at point (a) in Figure 1.17 and Va is start up voltage, typ. 18V. MOSFET switching is started after a mode judging (a-point~b-point).

Then auxiliary winding starts to supply power to IC. Capacitor CVCC which is connected between VCC and GND should be adjusted so that Vc, VCC voltage at point (c) ,does not go down below VCC undervoltage lock-out threshold (6V).

Example) Cvcc: 10uF @Vout35.5V, Iout700mA

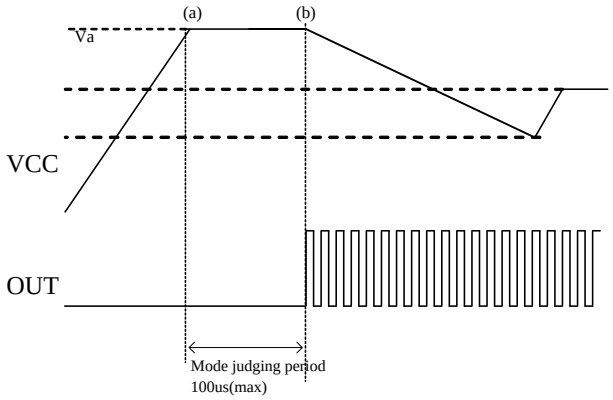


Figure 1.17 Start-up sequence

9. Precautions

9-1. FL1 and FL2 terminal

The value shown below is recommended for capacitor connected to FL1 and FL2.

- CFL1 = 0.1uF ~ 1uF
- CFL2 = 0.2uF ~ 2uF
- CFL1 ≦ CFL2 * 0.5

9-2. FUNC Terminal

Please connect 200kΩ between FUNC terminal and GND terminal for Step-down mode.
Although the resistance connected permits the accuracy within 5% of variation, and 100 ppm/°C, it recommends the accuracy within 1% of variation, and 100 ppm/°C.

10. Absolute maximum ratings

Absolute maximum ratings are values or ranges which can cause permanent damage. Please do not exceed this range even when start up or shut down.

Ta=25°C

Parameter	Symbol	Rating	unit	Applied terminal	Conditions
Power Supply Voltage	Vcc	-0.3 ~ 28.0	V	VCC	
Input Terminal Voltage	VI1	-0.3 ~ 6.0	V	FL1, FL2, ISE, VSE, FUNC	
Output Terminal Voltage	VO1	-0.3 ~ 28.0	V	OUT	
Power Dissipation *	PD	600	mW		Ta =25°C
Thermal Resistance *	θa	166.7	°C/W		
Operating Temperature	TOPR	-30 ~ 100	°C		
Storage Temperature	TSTG	-40 ~ 150	°C		

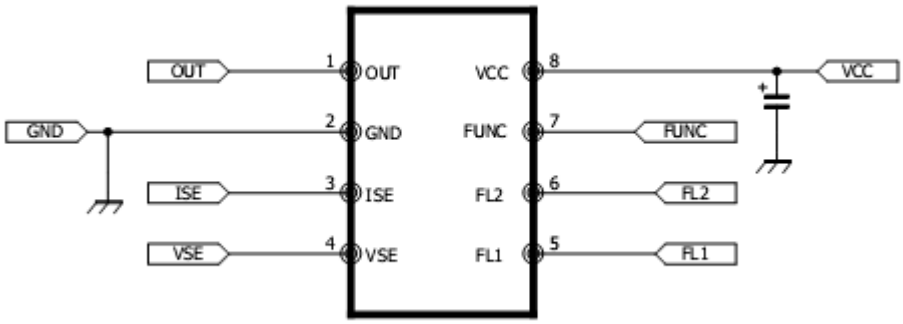
*Measured on JEDEC-JESD51-7 4-layer board.

11. Electrical characteristics

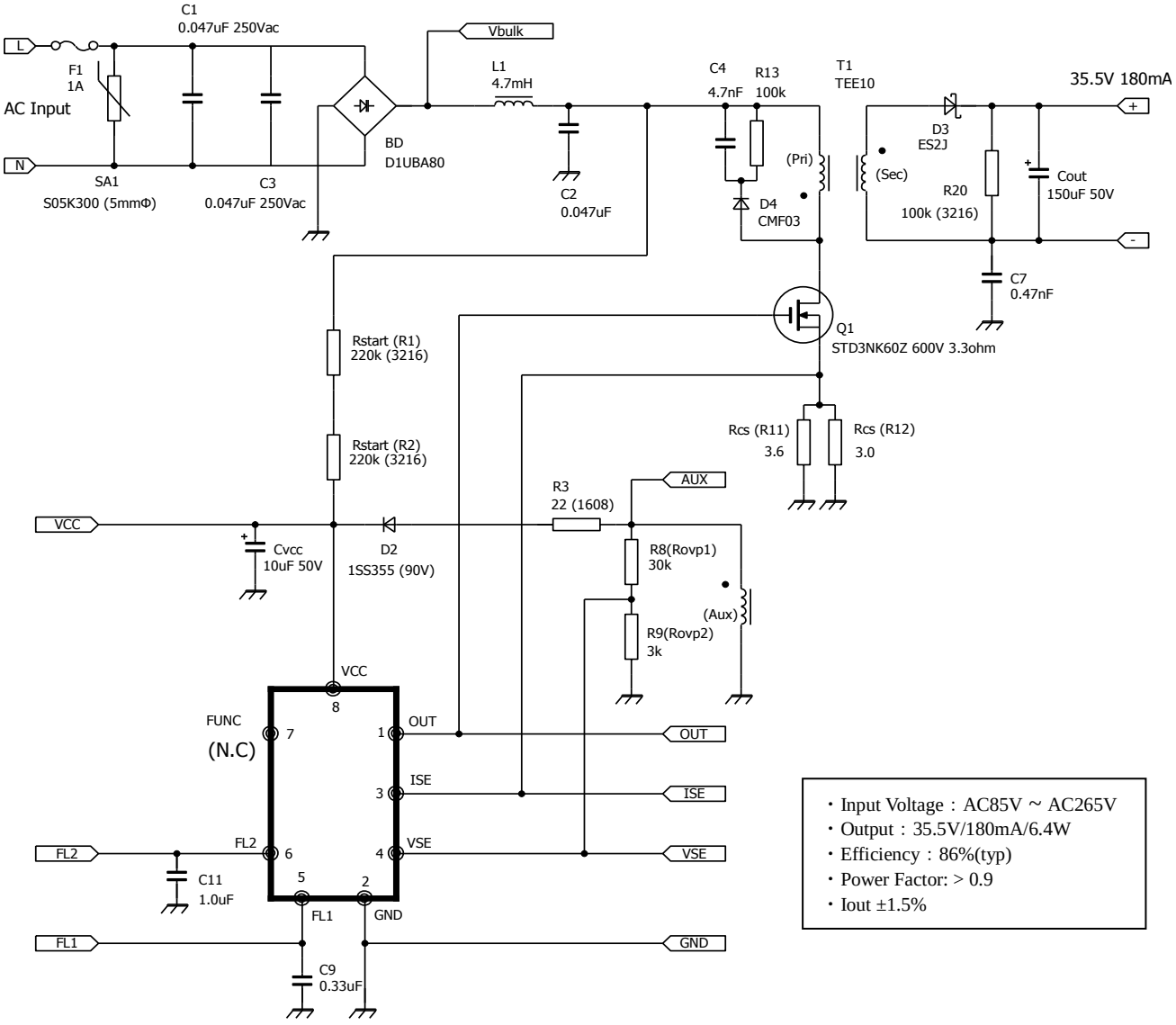
Unless otherwise specified, condition shall be GND=ISE=VSE=0V,VCC=16V, Ta=25°C

Parameter	Symbol	MIN	TYP	MAX	Unit	Conditions
VCC section						
VCC Input Voltage	VCC1	10	16	18	V	
VCC Startup Current	ICC1	—	30	80	uA	VCC=Startup voltage – 0.1V
VCC Operating supply current	ICC2	—	1.0	2.0	mA	
VCC Turn on threshold	Vst	15.5	18 .0	20.0	V	
VCC Turn off threshold	Vuvlo	5.0	6.0	7.5	V	
Gate driver section						
Output Low Resistance	RL	—	—	15	Ω	OUT-0.1V
Output High Current	IOH	40	—	—	mA	OUT<8V
Oscillator section						
Frequency	fosc	135	210	300	kHz	FL2=2.5V
Error Amplifier Section						
Reference Voltage	VREF	2.94	3.00	3.06	V	design assurance
Feedback Voltage	VFB	873	900	927	mV	VSE=1V,ISE=0.3V,FL2=2.5V
Transconductance	Gm	—	43	—	uA/V	FL1=0.9V
FL2 Operating range	Vfl2	0.5	—	4.0	V	
Zero Cross Detect Section						
VSE Threshold Voltage	VVSE	0.2	0.3	0.4	V	FL2=2.5V
FUNC section						
Threshold Voltage of Flyback mode	VFLY	3.2	—	4.5	V	
Threshold Voltage of StepDown mode	VStepD	1.45	—	2.85	V	
Threshold Voltage of Standby mode	Vstby	—	—	0.8	V	
Threshold High Voltage of PWM	VPWMH	1.45	—	4.5	V	
Threshold Low Voltage of PWM	VPWML	—	—	0.8	V	
FUNC Bias Current	IFUNC	8.7	10.0	12.5	uA	
Over Current Protection Section						
Threshold Voltage of Flyback	VOCP_FLY	1.45	1.60	1.75	V	FL2=2.5V
Threshold Voltage of StepDown	VOCP_StepD	0.65	0.80	0.95	V	FL2=2.5V
Minimum Off Time in OCP	tmin	40	70	120	us	
Leading edge blanking time	tleb1	—	200	—	ns	
Over Voltage Protection Section						
Threshold Voltage of VSE	VOVP_VSE	1.9	2.1	2.3	V	
Threshold Voltage of VCC	VOVP_VCC	21.0	22.7	24.5	V	
Leading edge blanking time	tleb2	—	600	—	ns	
Over Temperature Protection Section						
Threshold Temperature	TSD	135	150	165	°C	Junction temperature, design assurance

12. Test Circuit



13. Application circuit example



- Input Voltage：AC85V ~ AC265V
- Output：35.5V/180mA/6.4W
- Efficiency：86%(typ)
- Power Factor: > 0.9
- Iout ±1.5%

■Package and packing specification

[Applicability]
This specification applies to an IC package of the LEAD-FREE delivered as a standard specification.

1. Storage Conditions
Storage conditions required after opening the packing.
(1) Storage conditions for soldering. (Convection reflow[*1], IR/Convection reflow.[*1])
・Temperature : 5 ~ 30°C
・Humidity : 70% max.
・Period : In order to prevent oxidation of leads, please implement as soon as possible.
[*1]: Air or nitrogen environment.

2. Package outline specification

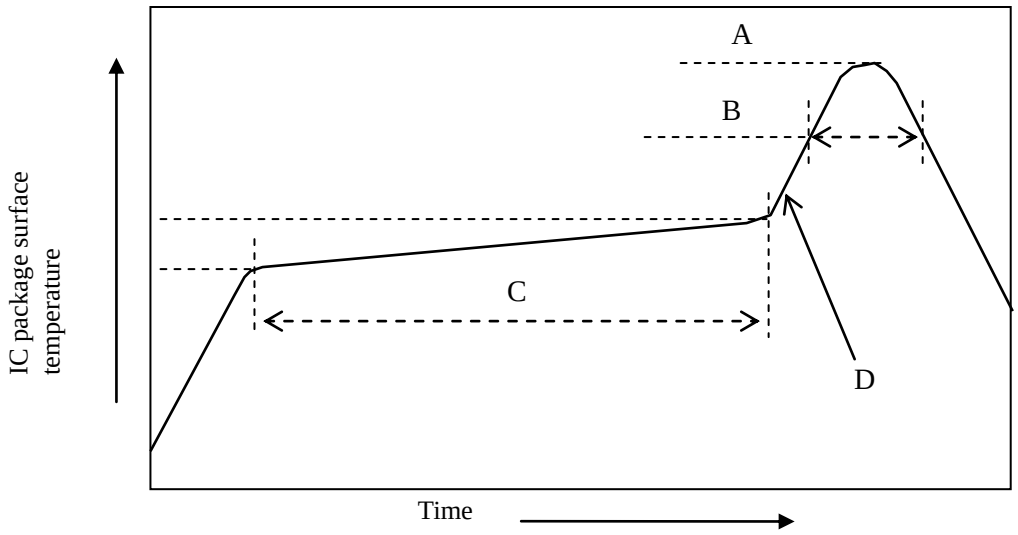
2-1. Package outline
Refer to the attached drawing.
2-2. LEAD FINISH
LEAD FREE TYPE (Sn-2%Bi)
2-3. Package weight
0.08g/pcs. About

3. Surface mount conditions
The following soldering conditions are recommended to ensure device quality.

3-1. Soldering
(1) Convection reflow or IR/Convection reflow. (one-time soldering or two-time soldering in air or nitrogen environment)
・Temperature and period :

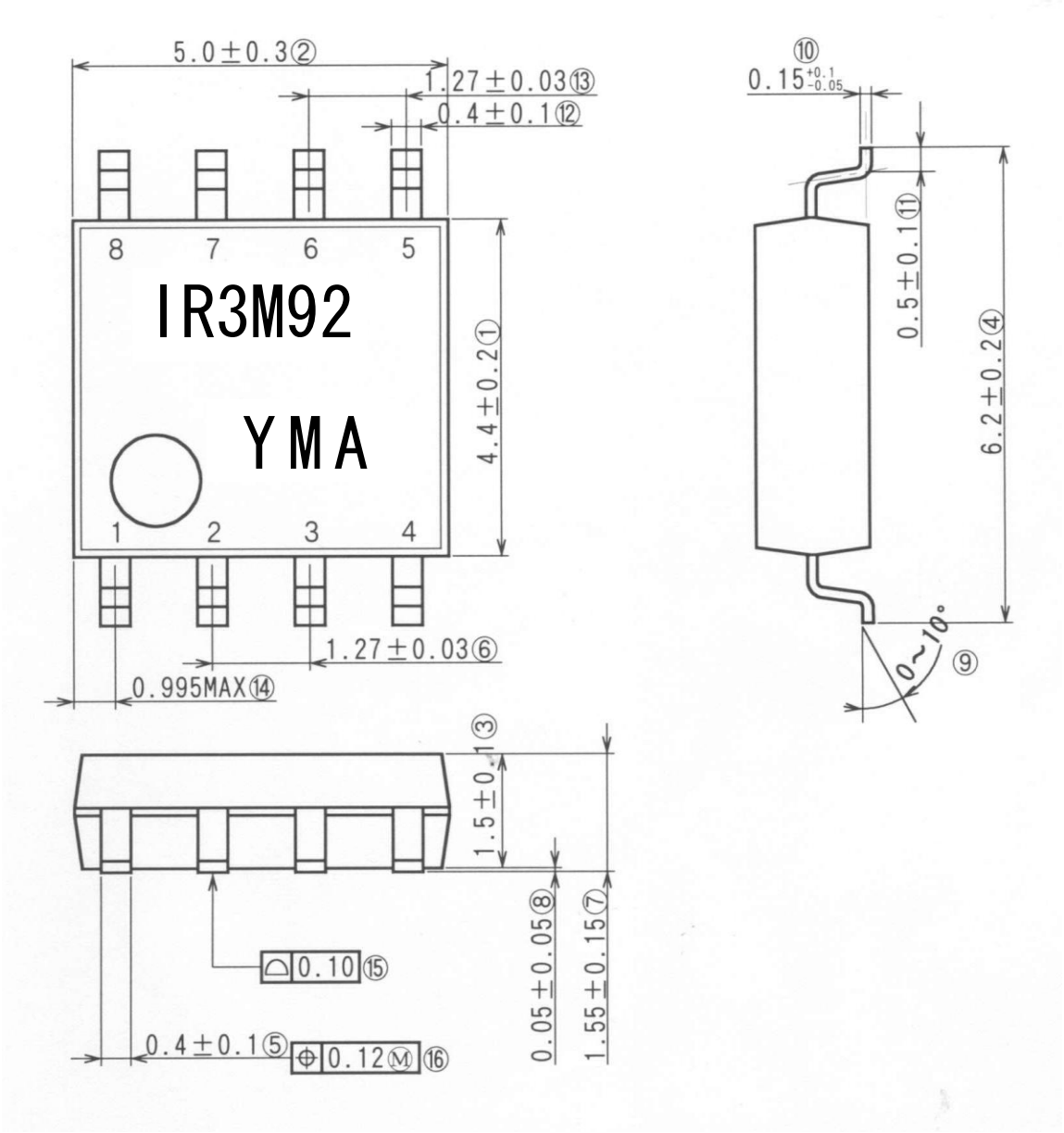
A)	Peak temperature	260°C max.
B)	Heating temperature	40 seconds as 230°C
C)	Preheat temperature	It is 150 to 180°C, and is 120 seconds Max.
D)	Temperature increase rate	It is 1 to 3°C/seconds

・Measuring point : IC package surface
・Temperature profile:



・Reflow times : 2 times max

4. Package outline



5. Markings

Marking details (The information on the package should be given as follows.)

(1) Product name : IR3M92

(2) Date code : (Example) YMA

Y → Denotes the production year. (Year code)

2012：B 2013：C 2014：D 2015：E

2016：F 2017：G 2018：H 2019：K

M → Denotes the production month. (1・2・~・8・9・O・N・D)

A → Denotes the production ref code.

パッケージ PKG	SOP008-P-0150	単位 UNIT	mm	NOTE

6. Packing specifications (Embossed carrier tape specifications)
The embossed carrier tape specifications supplied from SHARP are generally based on those described in JIS C 0806 (Japanese Industrial Standard)

6-1. Tape structure
The embossed carrier tape is made of conductive plastic. The embossed portions of the carrier tape are filled with IC packages and a top covering tape is used to enclose them.

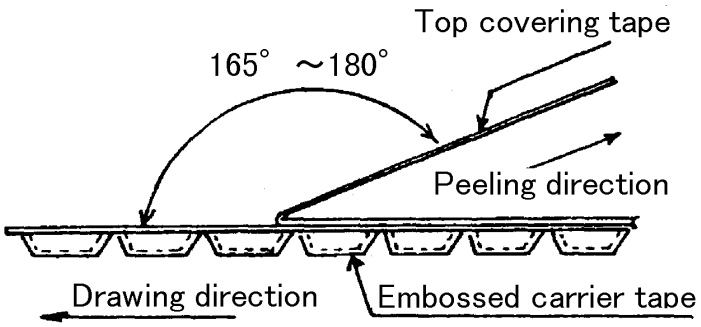
6-2. Taping reel and embossed carrier tape size
For the taping reel and embossed carrier tape sizes, refer to the attached drawing.

6-3. IC package enclosure direction in embossed carrier tape
The IC package enclosure direction in the embossed portion relative to the direction in which the tape is pulled is indicated by an index mark on the package (indicating the No. 1 pin) shown in the attached drawing.

6-4. Missing IC packages in embossed carrier tape
The number of missing IC packages in the embossed carrier tape per reel should be less 0.1 % of the total contained on the tape per reel, or There should never be consecutive missing IC packages.

6-5. Tape joints
There is no joint in an embossed carrier tape.

6-6. Peeling strength of the top covering tape
Peeling strength must meet the following conditions.
(1) Peeling angle at 165 ~ 180°
(2) Peeling strength at 0.1 ~ 1.0N.



6-7. Packing
(1) The top covering tape (leader side) at the leading edge of the embossed carrier tape, should be held in place with adhesive tape.
(2) The leading and trailing edges of the embossed carrier tape should be left empty in the attached drawing.
(3) The number of IC packages enclosed in the embossed carrier tape per reel should generally comply with the list given below.

Number of IC Packages / Reel	Number of IC Packages / Outer carton
1000 devices / Reel	1000 devices / Outer carton

6-8. Indications

The following should be indicated on the taping reel and the packing carton.

・Part Number (Product Name) ・Storage Quantity ・Manufacture's Name (SHARP)

6-9. Protection during transportation

The IC packages should have no deformation and deterioration of their electrical characteristics resulting from transportation.

7. Precautions for use

(1) Opening must be done on an anti-ESD treated workbench.
All workers must also have undergone anti-ESD treatment.

(2) The devices should be mounted within one year of the date of delivery.

8. Chemical substance information in the product

Product Information Notification based on Chinese law, Management Methods for Controlling Pollution by Electronic Information Products.

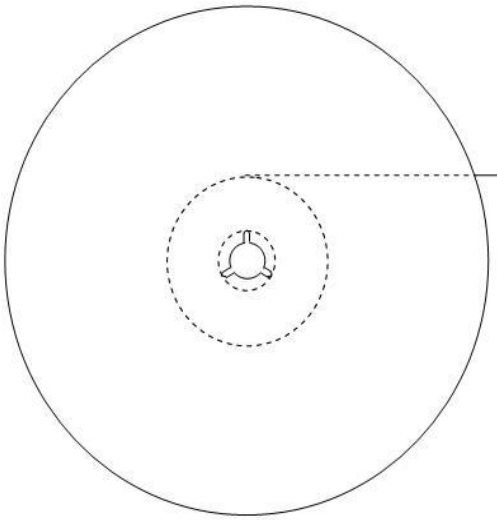
Names and Contents of the Toxic and Hazardous Substances or Elements in the Product

Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr(VI))	Polybrominated Biphenyls (PBB)	Polybrominated Diphenyl Ethers (PBDE)
○	○	○	○	○	○

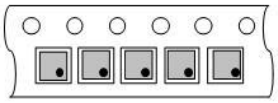
○ : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006.

× : indicates that the content of the toxic and hazardous substance in at least one homogeneous material of the part exceeds the concentration limit requirement as described in SJ/T 11363-2006 standard.

IC TAPING DIRECTION

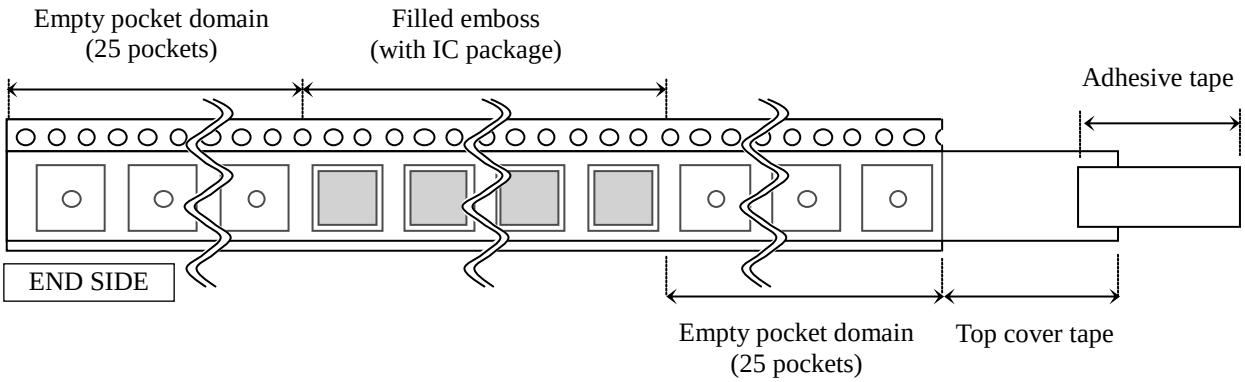


THE DRAWING DIRECTIN OF TAPE

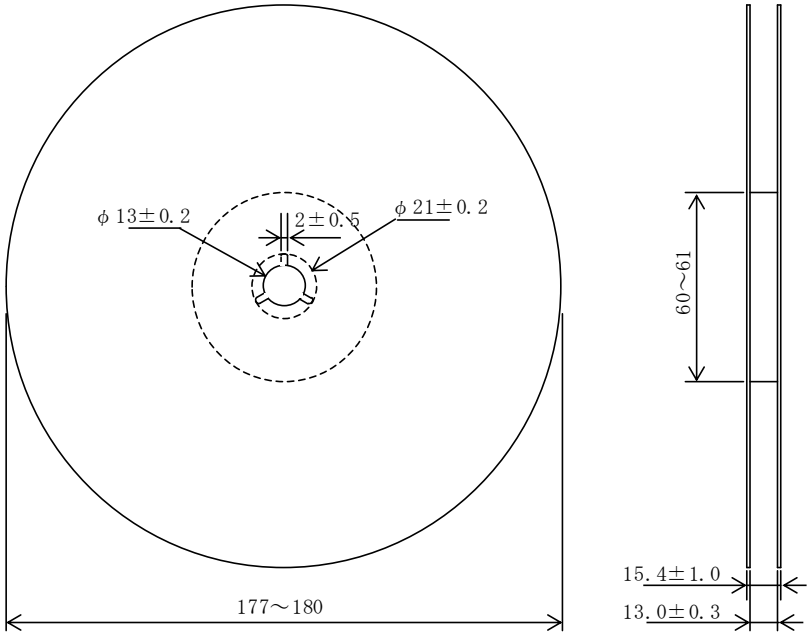


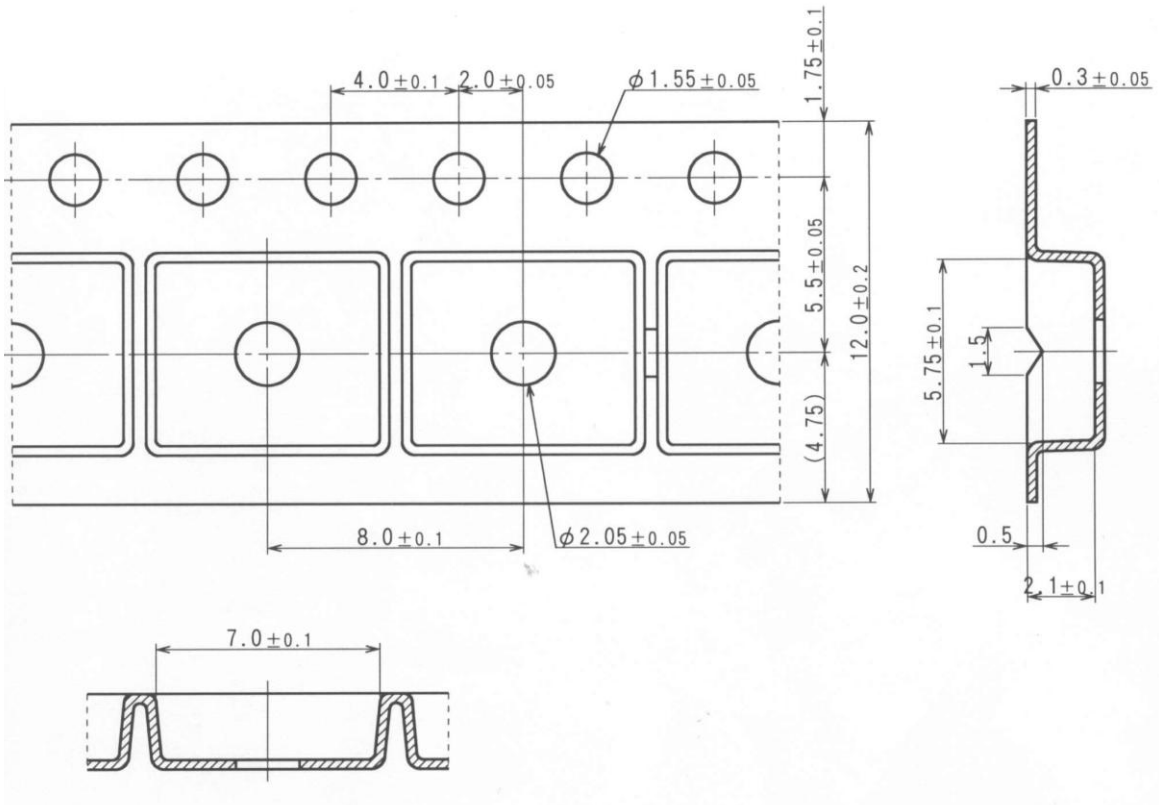
●Marking：First terminal position

LEADER SIDE AND END SIDE OF TAPE



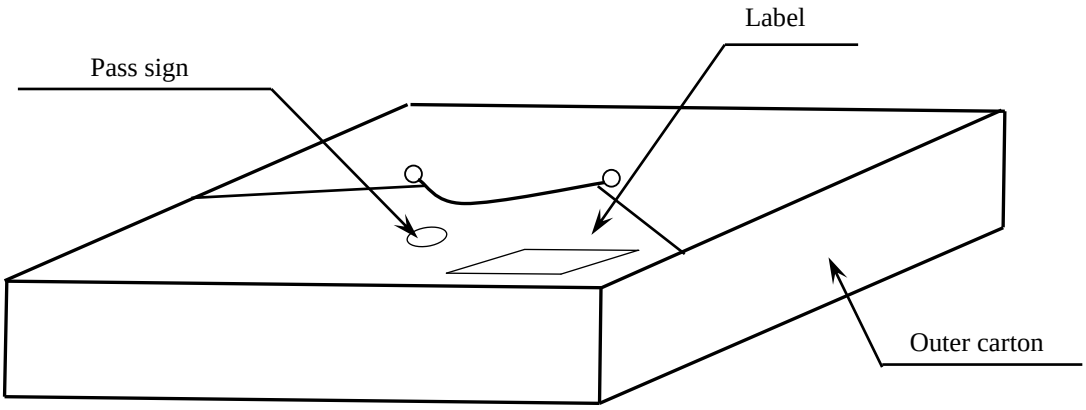
名称 NAME	Reel for embossed carrier tape	単位 UNIT	mm	NOTE





名称 NAME	Reel & Carrier tape drawing	単位 UNIT	mm	NOTE

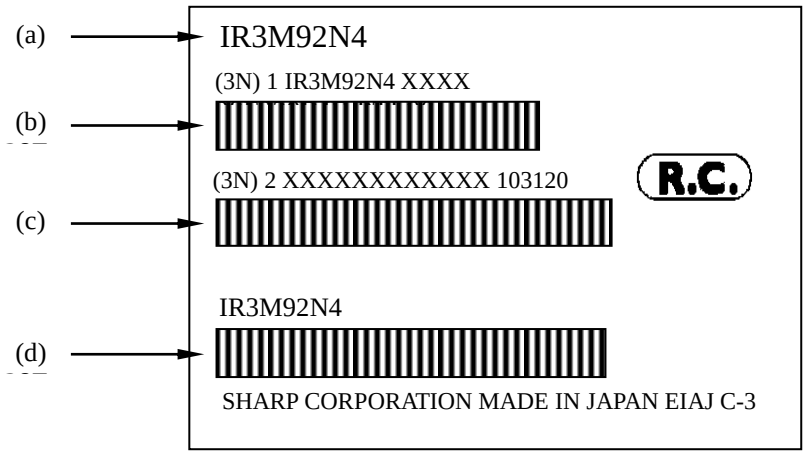
Packing



Pass sign

(Example)

Label



(a) Product name
(b) Product name・Quantity
(c) Serial No・Company code
(d) Part No. (SHARP)

"R.C." is Sharp's corporate logo indicating that the product is RoHS compliant.

名称 NAME	Packing specifications			NOTE
DRAWING NO.	—	単位 UNIT	mm	

■Important Notices

· The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.

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· Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:

(i) The devices in this publication are designed for use in general electronic equipment designs such as:

--- Personal computers
--- Office automation equipment
--- Telecommunication equipment [terminal]
--- Test and measurement equipment
--- Industrial control
--- Audio visual equipment
--- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

--- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
--- Traffic signals
--- Gas leakage sensor breakers
--- Alarm equipment
--- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

--- Space applications
--- Telecommunication equipment [trunk lines]
--- Nuclear power control equipment
--- Medical and other life support equipment (e.g., scuba).

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